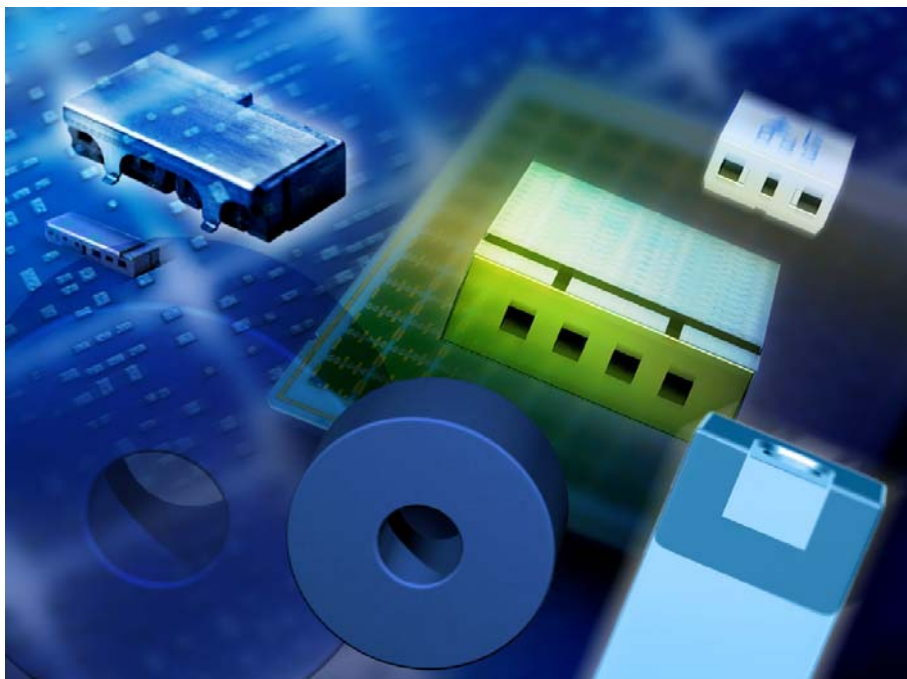


Data Sheet



Features

- SMD filter consisting of coupled resonators with stepped impedances
- extreme low losses
- high attenuations at GSM (900, 1800, 1900) bands
- stable performance over wide temperature range
- excellent reflow solderability, no migration effect due to copper/tin metallization

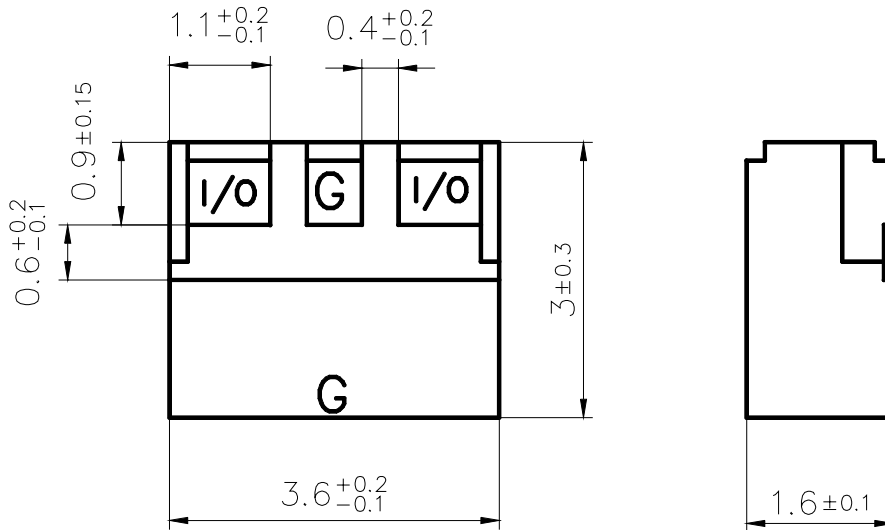
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Data Sheet

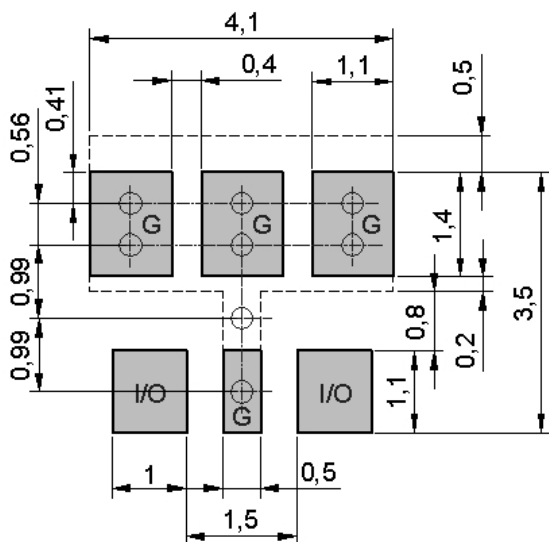
Component drawing



View from below onto the solder terminals and view from beside

Recommended footprint

Top view and marking



Y : year
WW : week



soldered areas

I/O Pads must be terminated with 50 Ω characteristic impedance

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Data Sheet

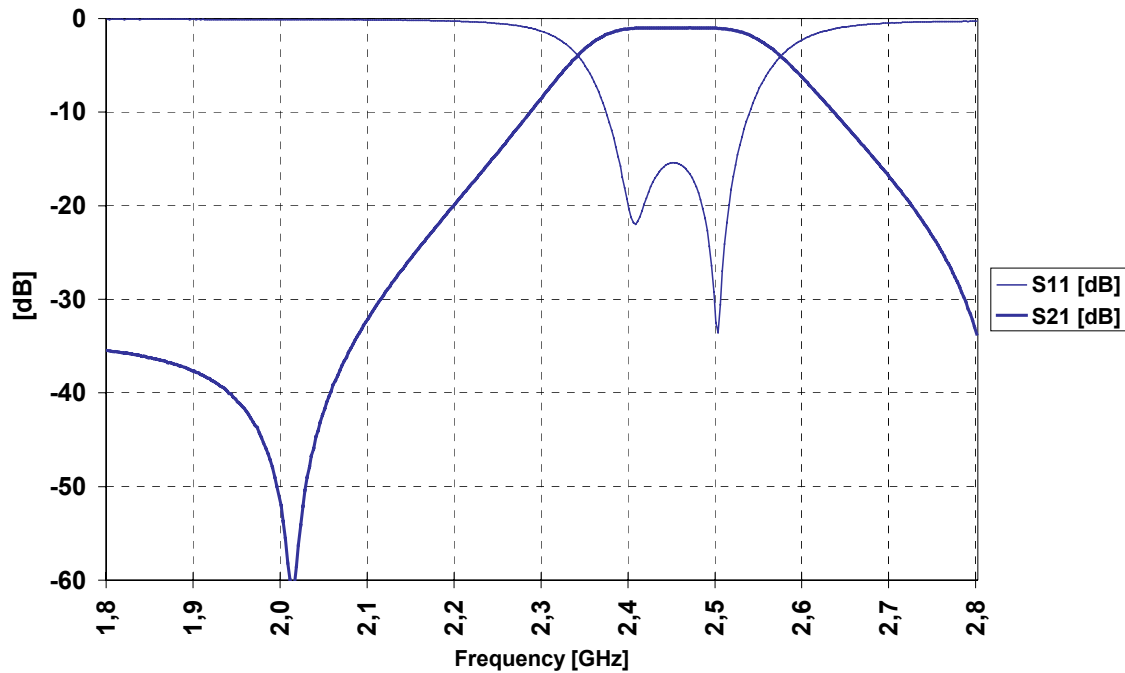
Characteristics over whole temperature range

		min.	typ.	max.	
Center frequency	f_c	-	2.4415	-	GHz
Insertion loss (2400 – 2483MHz)	α_{IL}		0.8	1.2	dB
Passband	B	83			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$		0.4	0.8	dB
Standing wave ratio	SWR		1.5	2.0	
Impedance (2400 – 2483MHz)	Z		50		Ω
Attenuation	α				
	at DC to 960 MHz	42	46		dB
	at 960 to 1990 MHz	32	35		dB
	at 2100 to 2170 MHz	20	23		dB

Maximum ratings

IEC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	T_{op}	- 40 / + 85	°C

Typical passband characteristic



Data Sheet

Processing information

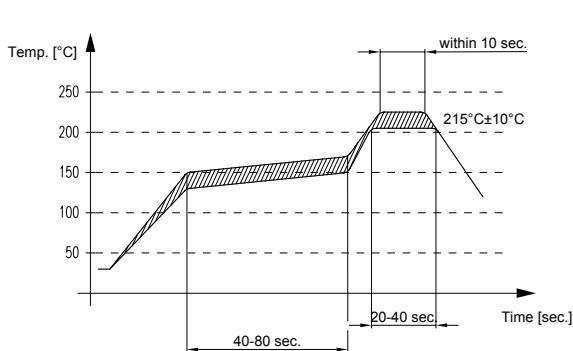
ZNr.: 527 (FILT95_2)

- Wettability acc. to IEC 68-2-58: $\geq 75\%$ (after aging)

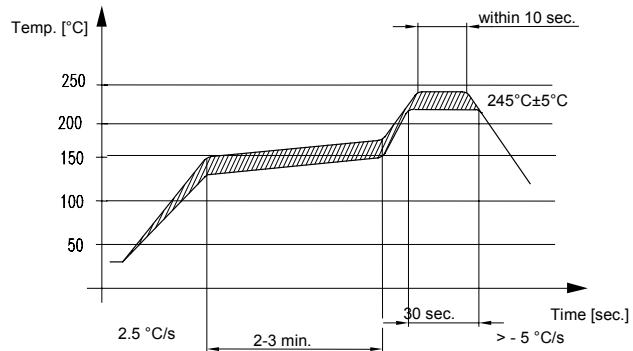
Soldering requirements

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	$^{\circ}\text{C}$ $^{\circ}\text{C}$

Recommended soldering conditions (infrared):



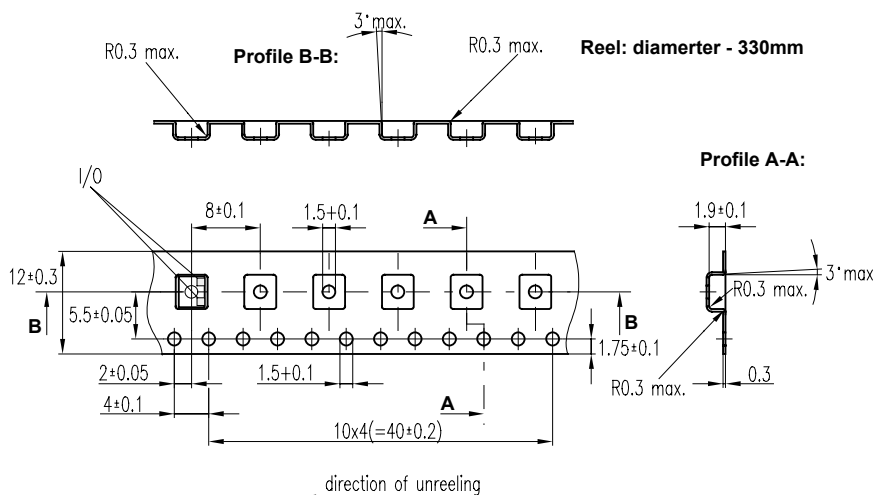
eutectic SnPb solder paste profile



leadfree solder paste profile

Delivery mode

- Blister tape acc. to IEC 286-3, polystyrol, grey
- Pieces/tape: 3000



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The information contained in this data sheet describes the type of component and shall not be considered as guaranteed characteristics. Purchase orders are subject to the General Conditions for the Supply of Products and Services of the Electrical and Electronics Industry recommended by the ZVEI (German Electrical and Electronic Manufacturers' Association), unless otherwise agreed.

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